

**Remarks**

In response to the Office Action dated November 29, 2005, in which the Examiner identified three distinct groups of inventions, and two species, Applicant hereby elects the invention associated with the Examiner's Invention I, namely Claims 7-10 associated with the method for thinning a wafer through abrasion, and species I, namely, a socket plate in which through holes are formed entirely through the thickness of the socket plate.

Respectfully submitted,

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By: 

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